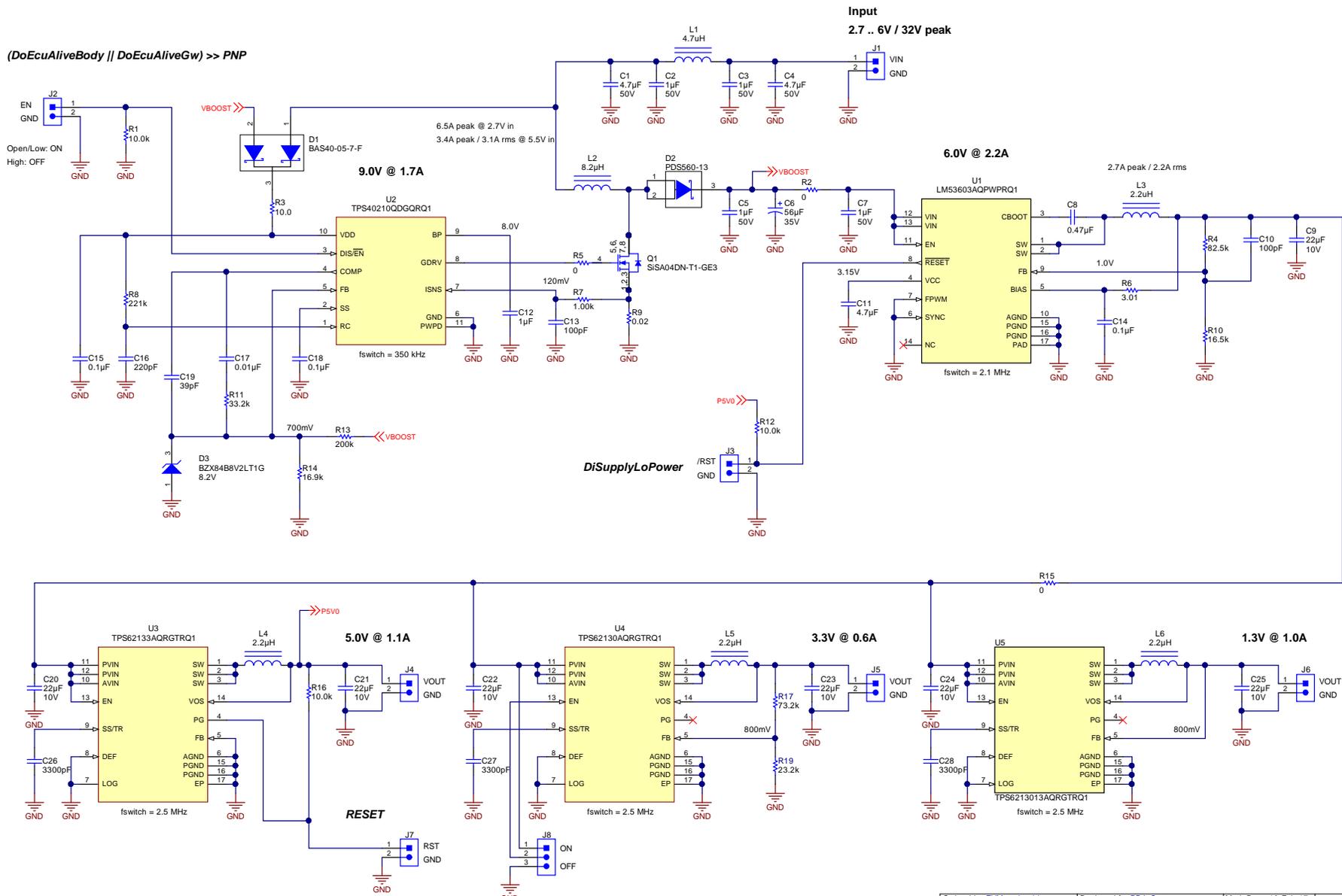


(DoEcuAliveBody || DoEcuAliveGw) >> PNP



Orderable: EVM_orderable	Designed for: PRJ_Customer	Mod. Date: 16-Feb-17
TID #: TID	Project File: PRJ Title	
Number: PRJ_Number Rev: SCH	Sheet Title:	
SWN Rev: Version control disabled	Assembly Variant [No Variations]	Sheet: 1 of 2
Drawn By: Fred Illguth	File: TIDA-01412_Automotive_uC_Power_Sch.Doc Size: B	http://www.ti.com
Engineer: PRJ_Engineer	Contact: TechSupport	

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